



MOS 数据手册

NPM2033LA

20V Complementary MOS

Rev. 1.0

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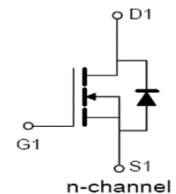
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NMOS 20V 5A/PMOS -20V -4.2A NPM2033LA

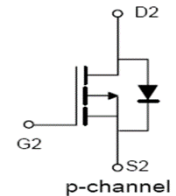
产品特性 Features

- | | |
|------------------|--|
| ◆ 先进沟槽工艺技术 | Advanced Trench Technology |
| ◆ 超低栅极电荷 | Super Low Gate Charge |
| ◆ 超低 Ron 高密度单元设计 | High Density Cell Design for Ultra Low Rdson |
| ◆ RoHS 产品 | RoHS Product |

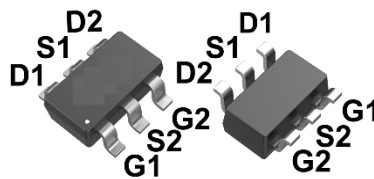


应用领域 Applications

- | | |
|-------------|--------------------------|
| ◆ 负载开关 | Load Switching |
| ◆ 脉宽调制器 | PWM |
| ◆ DC/DC 转换器 | DC/DC Converter |
| ◆ 高频开关 | High Frequency Switching |



关键参数与封装信息 Key Performance and Package Parameters



SOT23-6L

产品型号 Part No.	封装 Package	漏极-源极电压 V _{ds}	漏极电流 I _d	导通电阻 R _{DS(on)} Typ.	印记 Marking
NPM2033LA	SOT23-6L	20V	5A	22.5mΩ @ V _{GS} = 4.5V	2033LA
		-20V	-4.2A	31.5mΩ @ V _{GS} = -4.5V	

最大额定值 Maximum Ratings

参数 Parameter	符号 Symbol	数值 NMOS	数值 PMOS	单位 Unit
最高漏极-源极直流电压 Drain to Source Voltage	V _{DS}	20	-20	V
最高栅源电压 Gate to Source Voltage	V _{GS}	±12	±12	V
连续漏极电流 Drain Current-Continuous, Limited by T _{vjmax} TC = 25°C TC = 100°C	I _D	5 3.1	-4.2 -2.7	A
最大脉冲漏极电流 Pulse Drain Current ^① PW ≤ 300μs, Duty Cycle ≤ 2%	I _{Dpuls}	25	-21	A
二极管正向电流 Diode Forward Current, Limited by T _{vjmax} TC = 25°C	I _S /I _{SM}	5/25	-4.2/-21	A
最大耗散功率 Maximum Power Dissipation TC = 25°C TC = 100°C	P _D	1.25 0.5	1.25 0.5	W
结温 Operating Junction Temperature	T _J	-55...+150	-55...+150	°C
存储温度 Storage Temperature	T _{stg}	-55...+150	-55...+150	°C
最高焊接温度 Maximum Soldering Temperature		260	260	°C

① 脉冲宽度由最高结温限制 Pulse width limited by maximum junction temperature

热阻特性 Thermal Resistance

参数 Parameter	符号 Symbol	数值 (最大) Max. Value	单位 Unit
结到环境热阻 Thermal Resistance Junction to Ambient ^②	R _{θJA}	100	°C /W

② Device on 40mm x 40mm x 1.5mm epoxy PCB FR4 with 6cm² (one layer, 7μm thick) copper area for drain connection. PCB is vertical in still air.

NMOS 电气特性 Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

项目 Parameter	符号 Symbol	测试条件 Conditions	数值 Value			单位 Unit
			Min.	Typ.	Max.	
漏-源击穿电压 Drain to Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	20	-	-	V
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=20V, V_{GS}=0V$ $T_J=25^\circ\text{C}$ $T_J=150^\circ\text{C}$	-	-	1 100	μA
栅极漏电流 Gate to Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 12V$	-	-	± 100	nA
阈值电压 Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	0.4	-	1.1	V
静态导通电阻 Drain to Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=4A$	-	22.5	29	$m\Omega$
		$V_{GS}=2.5V, I_D=3A$	-	28	39	$m\Omega$
正向压降 Diode Forward Voltage	V_{SD}	$I_S=5A, V_{GS}=0V$	-	-	1.4	V
输入电容 Input Capacitance	C_{iss}	$V_{DS}=10V$ $V_{GS}=0V$ $f=1MHz$	-	458	-	pF
输出电容 Output Capacitance	C_{oss}		-	59.5	-	pF
反向传输电容 Reverse Transfer Capacitance	C_{rss}		-	51.8	-	pF
栅极电荷总量 Total Gate Charge	Q_g	$V_{DS}=10V$ $V_{GS}=4.5V$ $I_{DS}=4A$	-	5.83	-	nC
栅极-源极电荷 Gate to Source Charge	Q_{gs}		-	0.67	-	
栅极-漏极电荷 Gate to Drain Charge	Q_{gd}		-	1.75	-	
开启延迟时间 Turn-On Delay Time	$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{DD}=10V, I_D=3A$ $V_{GS}=4.5V, R_G=3\Omega$	-	9	-	ns
上升时间 Rise Time	t_r		-	69	-	
关断延迟时间 Turn-Off Delay Time	$t_{d(off)}$		-	63	-	
下降时间 Fall Time	t_f		-	26	-	
反向恢复时间 Reverse Recovery Time	t_{rr}	$I_F=3A, di/dt=100A/\mu s$	-	15	-	ns
反向恢复电荷 Reverse Recovery Charge	Q_{rr}		-	1	-	nC

NMOS 特征曲线 Characteristic Curve

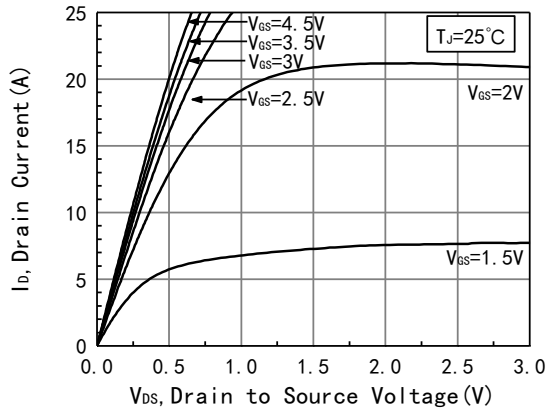


Figure 1. Typical Output Characteristics

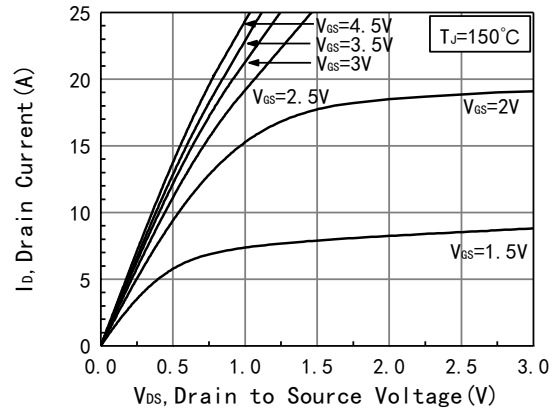


Figure 2. Typical Output Characteristics

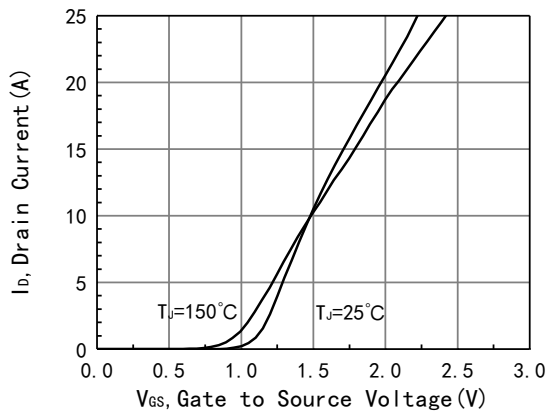


Figure 3. Typical Transfer Characteristics

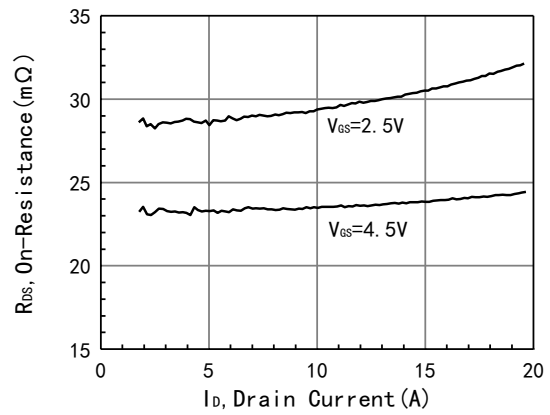


Figure 4. $R_{DS(on)}$ vs. I_D

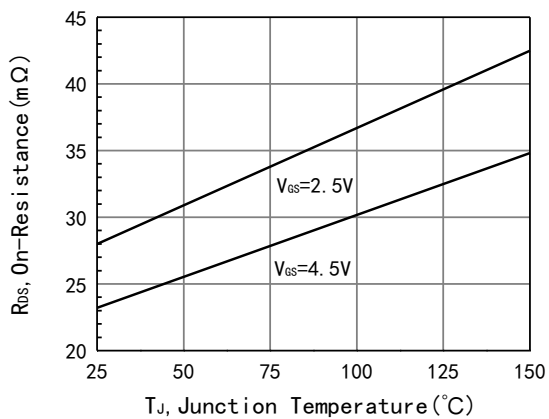


Figure 5. $R_{DS(on)}$ vs. T_J

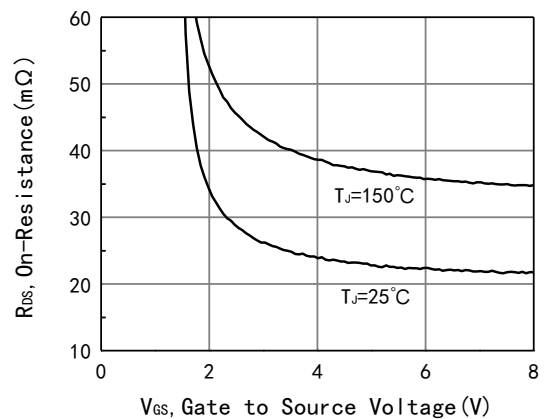


Figure 6. $R_{DS(on)}$ vs. V_{GS}

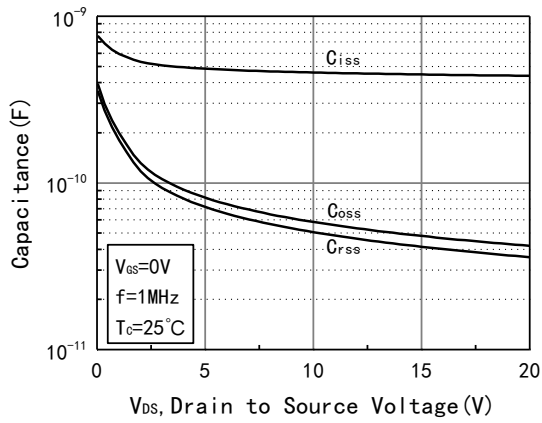


Figure 7. Capacitance vs. Vds

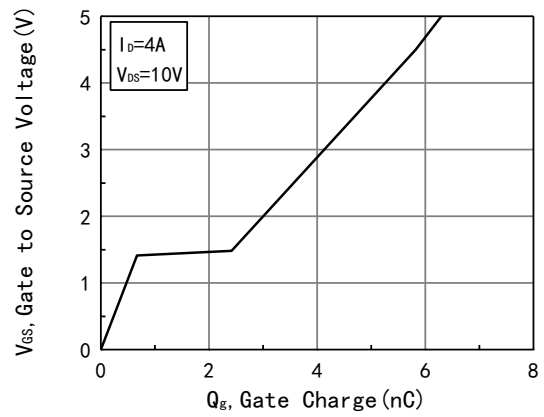


Figure 8. Gate Charge Characteristic

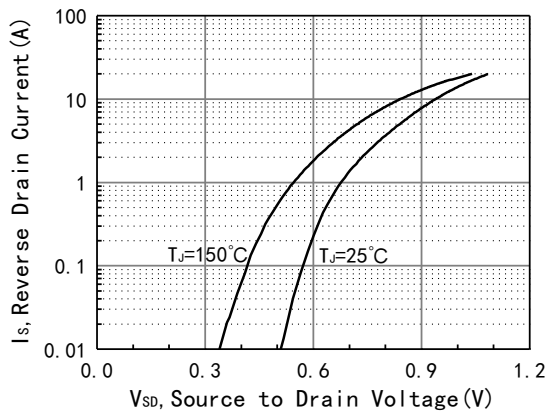


Figure 9. Diode Forward Characteristic

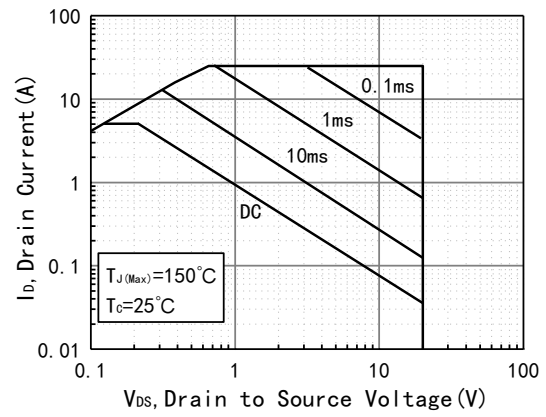


Figure 10. Safe Operating Area

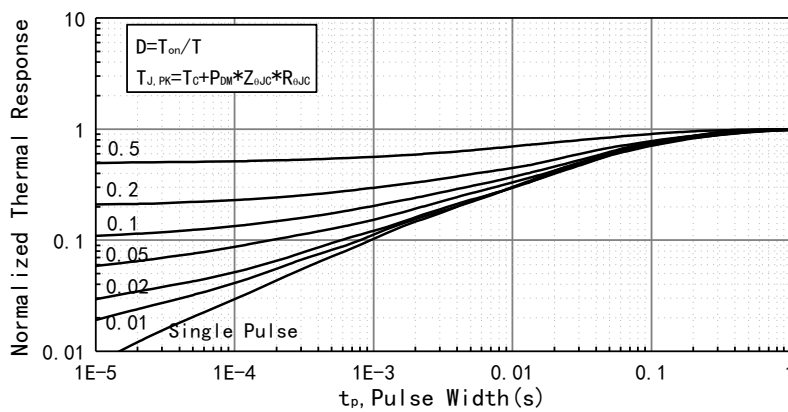


Figure 11. Normalized Maximum Transient Thermal Impedance

Notes:

Pulse Test: Pulse Width ≤ 380μs, Pulse Delay ≤ 200μs.

PMOS 电气特性 Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise noted)

项目 Parameter	符号 Symbol	测试条件 Conditions	数值 Value			单位 Unit
			Min.	Typ.	Max.	
漏-源击穿电压 Drain to Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-20	-	-	V
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-20V, V_{GS}=0V$ $T_J=25^\circ\text{C}$ $T_J=150^\circ\text{C}$	-	-	-1 -100	μA
栅极漏电流 Gate to Source Leakage Current	I_{GSS}	$V_{DS}=0V, V_{GS}=\pm 12V$	-	-	± 100	nA
阈值电压 Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.4	-	-0.9	V
静态导通电阻 Drain to Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=-4.5V, I_D=-3A$	-	31.5	40	$m\Omega$
		$V_{GS}=-2.5V, I_D=-2A$	-	37.5	52	$m\Omega$
正向压降 Diode Forward Voltage	V_{SD}	$I_S=-4A, V_{GS}=0V$	-	-	-1.4	V
输入电容 Input Capacitance	C_{iss}	$V_{DS}=-10V$ $V_{GS}=0V$ $f=1\text{MHz}$	-	935	-	pF
输出电容 Output Capacitance	C_{oss}		-	112	-	pF
反向传输电容 Reverse Transfer Capacitance	C_{rss}		-	108	-	pF
栅极电荷总量 Total Gate Charge	Q_g	$V_{DS}=-10V$ $V_{GS}=-4.5V$ $I_{DS}=-3A$	-	17	-	nC
栅极-源极电荷 Gate to Source Charge	Q_{gs}		-	2.5	-	
栅极-漏极电荷 Gate to Drain Charge	Q_{gd}		-	4.6	-	
开启延迟时间 Turn-On Delay Time	$t_{d(on)}$	$T_J=25^\circ\text{C}$ $V_{DD}=-10V, I_D=-3A$ $V_{GS}=-4.5V, R_G=3\Omega$	-	14	-	ns
上升时间 Rise Time	t_r		-	31	-	
关断延迟时间 Turn-Off Delay Time	$t_{d(off)}$		-	41	-	
下降时间 Fall Time	t_f		-	34	-	
反向恢复时间 Reverse Recovery Time	t_{rr}	$I_F=-3A, di/dt=100A/\mu s$	-	35	-	ns
反向恢复电荷 Reverse Recovery Charge	Q_{rr}		-	24	-	nC

PMOS 特征曲线 Characteristic Curve

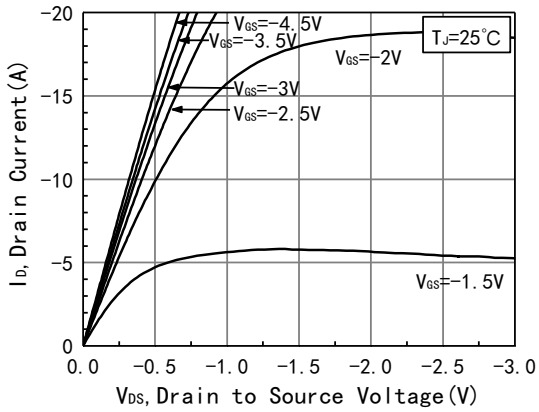


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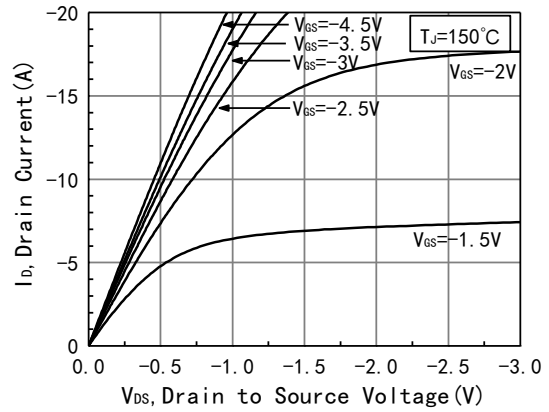


Figure 2. Typical Output Characteristics

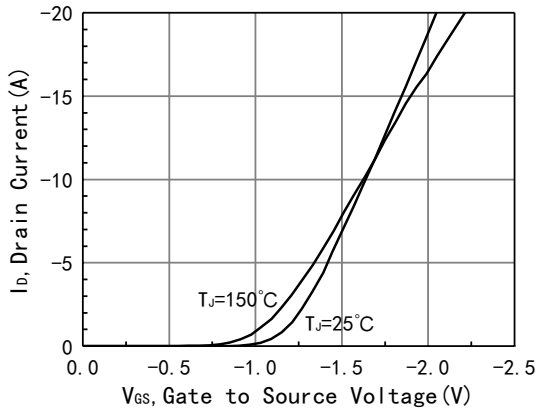


Figure 3. Typical Transfer Characteristics

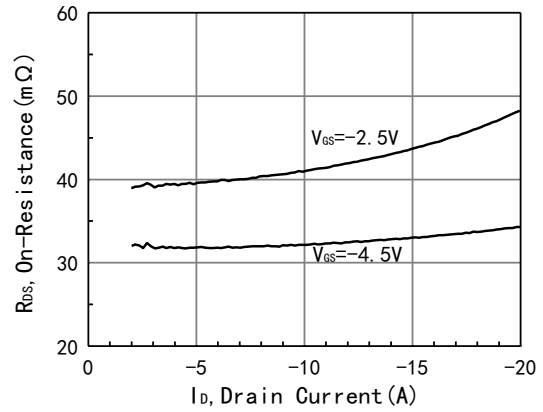


Figure 4. $R_{DS(on)}$ vs. I_D

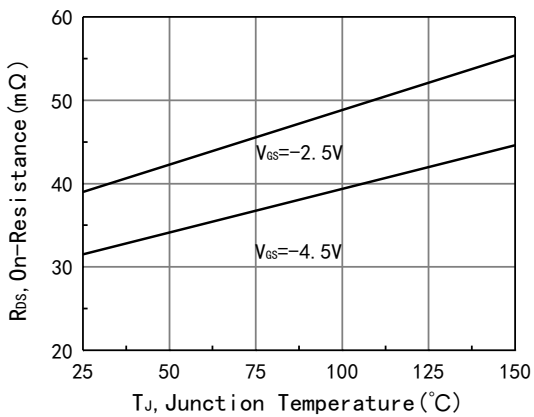


Figure 5. $R_{DS(on)}$ vs. T_J

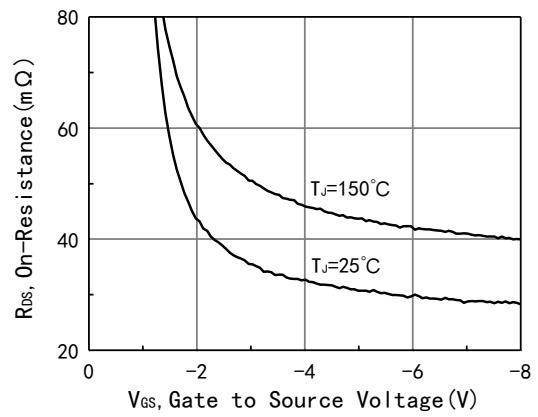


Figure 6. $R_{DS(on)}$ vs. V_{GS}

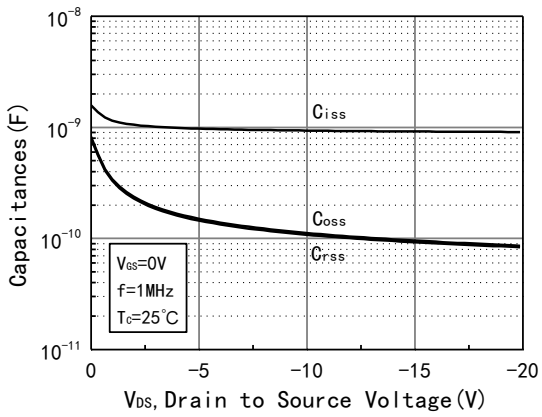


Figure 7. Capacitance vs. Vds

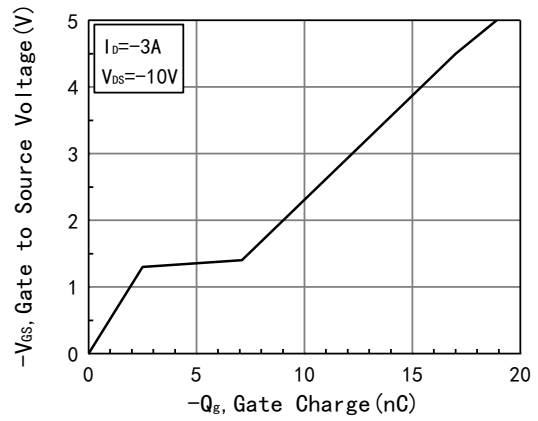


Figure 8. Gate Charge Characteristic

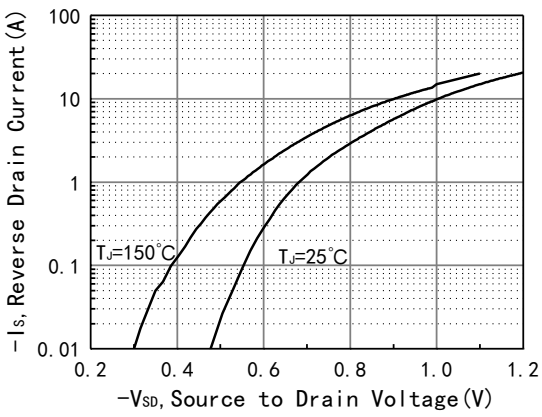


Figure 9. Diode Forward Characteristic

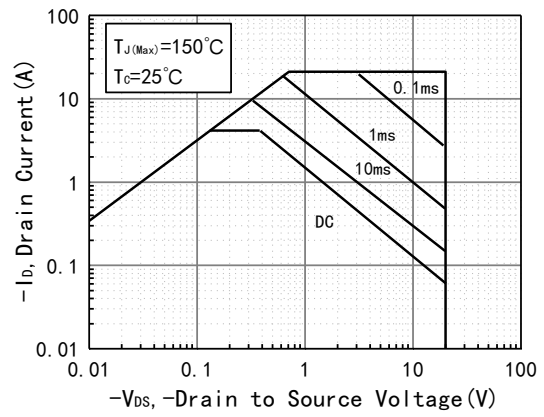


Figure 10. Safe Operating Area

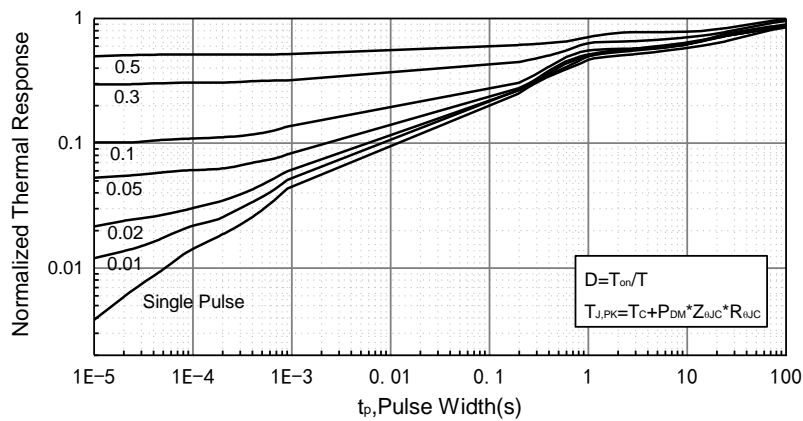
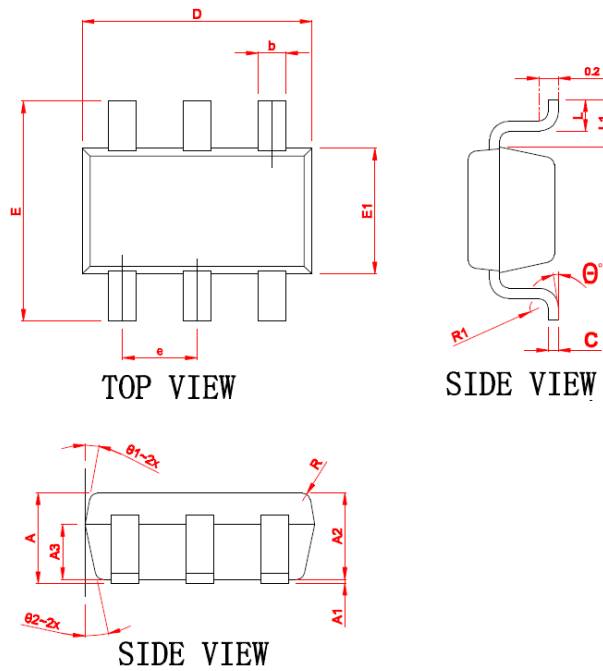


Figure 11. Normalized Maximum Transient Thermal Impedance

Notes:

Pulse Test: Pulse Width ≤ 380μs, Pulse Delay ≤ 200μs.

外形尺寸 Mechanical Data: SOT23-6L



Symbol	MILLIMETER		
	MIN	NOM	MAX
A	1.10	1.15	1.25
*A1	0.02	0.06	0.10
*A2	1.05	1.10	1.15
A3	0.60	0.65	0.70
*b	0.32	0.35	0.48
*c	0.152 REF		
*D	2.87	2.92	2.92
*E	2.60	2.80	3.00
*E1	1.55	1.60	1.65
*e	0.95 BSC		
*L	0.35	0.45	0.55
L1	0.60 REF		
R	0.10 REF		
R1	0.12 REF		
* θ	0°	3°	8°
θ 1	7° BSC		
θ 2	10° BSC		

历史版本

版本号	时间	修改内容
V1.0	2022年8月	初始版本